

PC922

High Power OPIC Photocoupler

* Lead forming type (I type) and taping reel type (P type) are also available. (PC922I/PC922P)

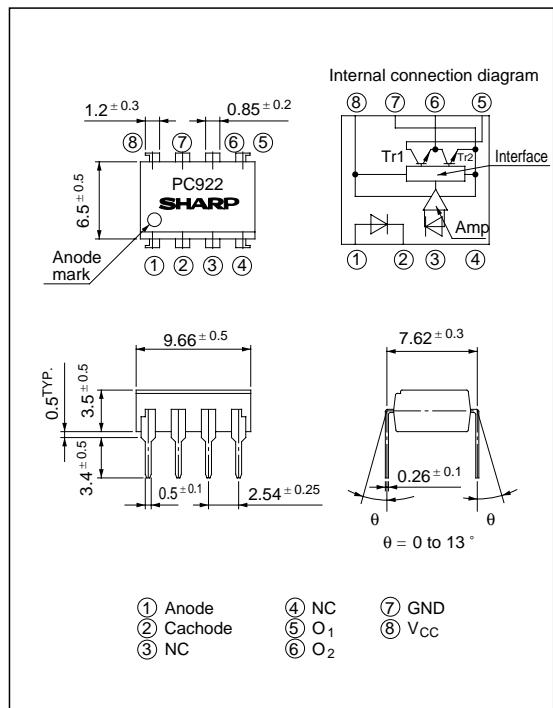
** TÜV (VDE 0884) approved type is also available as an option.

■ Features

1. Built-in base amplifier for inverter drive
2. High power (I_{O1} : MAX. 0.5A (DC))
(I_{O2P} : MAX. 2.0A (pulse))
3. High isolation voltage between input and output (V_{iso} : 5 000V_{rms})
4. High noise reduction type
5. High speed response (t_{PHL}, t_{PLH} : MAX. 5μs)
6. High sensitivity (I_{FLH} : MAX. 3mA)
7. Recognized by UL, file No. E64380

■ Outline Dimensions

(Unit : mm)



* "OPIC" (Optical IC) is a trademark of the SHARP Corporation.
An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.

■ Absolute Maximum Ratings

(Ta = T_{opr} unless otherwise specified)

Parameter		Symbol	Rating	Unit
Input	Forward current	I _F	25	mA
	* ¹ Reverse voltage	V _R	6	V
Output	Supply voltage	V _{CC}	18	V
	O ₁ output current	I _{O1}	0.5	A
	* ² O ₁ peak output current	I _{O1P}	1.0	A
	O ₂ output current	I _{O2}	0.6	A
	* ² O ₂ peak output current	I _{O2P}	2.0	A
	O ₁ output voltage	V _{O1}	18	V
	Power dissipation	P _O	500	mW
	Total power dissipation	P _{tot}	550	mW
	* ³ Isolation voltage	V _{iso}	5 000	V _{rms}
	Operating temperature	T _{opr}	- 20 to + 80	°C
	Storage temperature	T _{stg}	- 55 to + 125	°C
	* ⁴ Soldering temperature	T _{sol}	260	°C

*1 Ta = 25°C

*2 Pulse width <= 5μs, Duty ratio: 0.01

*3 40 to 60% RH, AC for 1 minute,
Ta = 25°C

*4 For 10 seconds

^{*} In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any of SHARP's devices, shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest version of the device specification sheets before using any SHARP's device.

■ Electro-optical Characteristics

(Ta = T_{opr} unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Fig.	
Input	Forward voltage	V _{F1}	T _a = 25°C, I _F = 5mA	-	1.1	1.4	V	-	
		V _{F2}	T _a = 25°C, I _F = 0.2mA	0.6	0.9	-	V	-	
	Reverse current	I _R	T _a = 25°C, V _R = 3V	-	-	10	μA	-	
	Terminal capacitance	C _t	T _a = 25°C, V = 0, f = 1kHz	-	30	250	pF	-	
Output	Operating supply voltage	V _{CC}		5.4	-	13	V	-	
	O ₁ low level output voltage	V _{O1L}	V _{CC} = 6V, I _{O1} = 0.4A, R _{L2} = 10Ω, I _F = 5mA	-	0.2	0.4	V	1	
	O ₂ high level output voltage	V _{O2H}	V _{CC} = 6V, I _{O2} = -0.4A, I _F = 5mA	4.5	5.0	-	V	2	
	O ₂ low level output voltage	V _{O2L}	V _{CC} = 6V, I _{O2} = 0.5A, I _F = 0	-	0.2	0.4	V	-	
	O ₁ leak current	I _{O1L}	V _{CC} = 13V, I _F = 0	-	-	200	μA	3	
	O ₂ leak current	I _{O2L}	V _{CC} = 13V, I _F = 5mA	-	-	200	μA	4	
	High level supply current	I _{CH}	T _a = 25°C, V _{CC} = 6V, I _F = 5mA	-	9	13	mA	-	
			V _{CC} = 6V, I _F = 5mA	-	-	17	mA	-	
Transfer characteristics	Low level supply current		I _{CL}	T _a = 25°C, V _{CC} = 6V, I _F = 0	-	11	15	mA	-
				V _{CC} = 6V, I _F = 0	-	-	20	mA	-
	*5 “Low→High” threshold input current		I _{FLH}	T _a = 25°C, V _{CC} = 6V, R _{L1} = 5Ω, R _{L2} = 10Ω	0.3	1.5	3.0	mA	5
				V _{CC} = 6V, R _{L1} = 5Ω, R _{L2} = 10Ω	0.2	-	5.0	mA	5
	Isolation resistance		R _{ISO}	T _a = 25°C, DC = 500V 40 to 60% RH	5 x 10 ¹⁰	10 ¹¹	-	Ω	-
	Response time	“Low→High” propagation delay time	t _{PLH}	T _a = 25°C, V _{CC} = 6V I _F = 5mA R _{L1} = 5Ω R _{L2} = 10Ω	-	2	5	μs	6
		“High→Low” propagation delay time	t _{PHL}		-	2	5	μs	
		Rise time	t _r		-	0.2	1	μs	
		Fall time	t _f		-	0.1	1	μs	
	Instantaneous common mode rejection voltage “Output : High level”		C _{MH}	T _a = 25°C, V _{CM} = 600V _(peak) I _F = 5mA, R _{L1} = 470Ω, R _{L2} = 1kΩ, Δ V _{O2H} = 0.5V	-1 500	-	-	V/ μs	7
	Instantaneous common mode rejection voltage “Output : Low level”		C _{ML}	T _a = 25°C, V _{CM} = 600V _(peak) I _F = 0, R _{L1} = 470Ω, R _{L2} = 1kΩ, Δ V _{O2L} = 0.5V	1 500	-	-	V/ μs	7

*5 I_{FLH} represents forward current when output goes from low to high.

■ Truth Table

Input	O ₂ Output	Tr. 1	Tr. 2
ON	High level	ON	OFF
OFF	Low level	OFF	ON

■ Test Circuit

Fig. 1

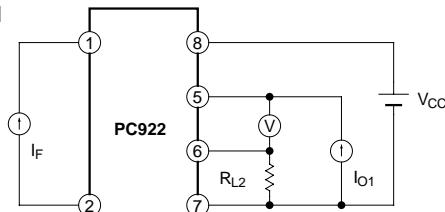


Fig. 3

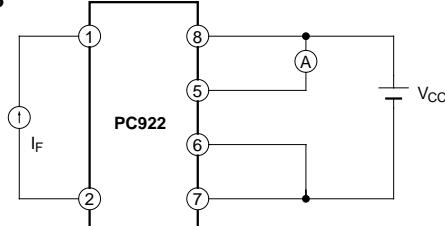


Fig. 5

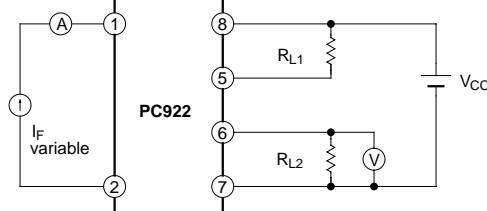


Fig. 7

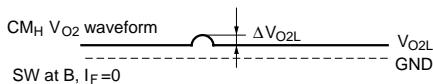
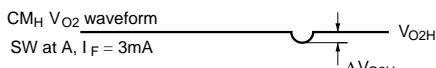
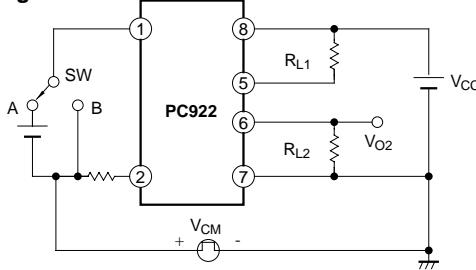


Fig. 2

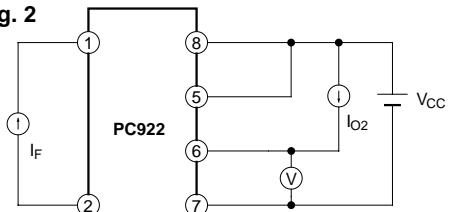


Fig. 4

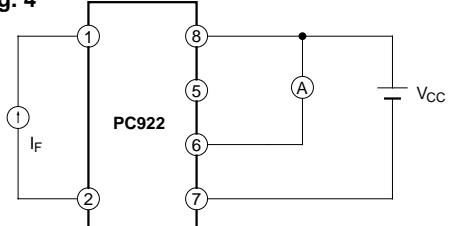


Fig. 6

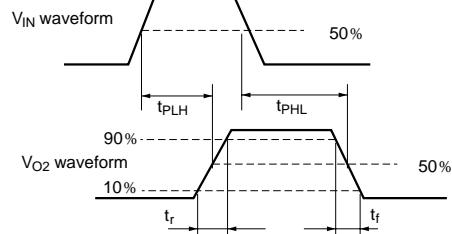
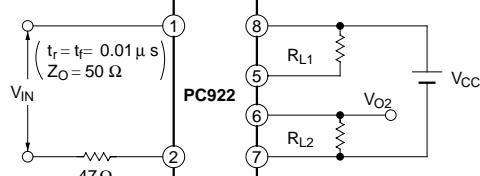
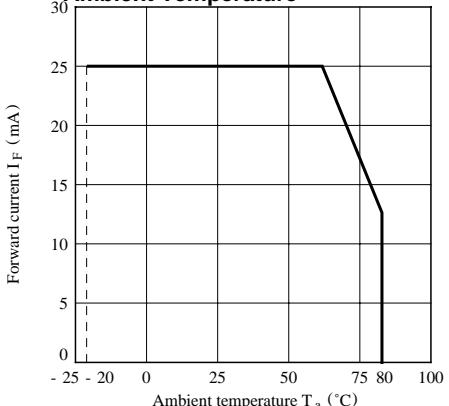
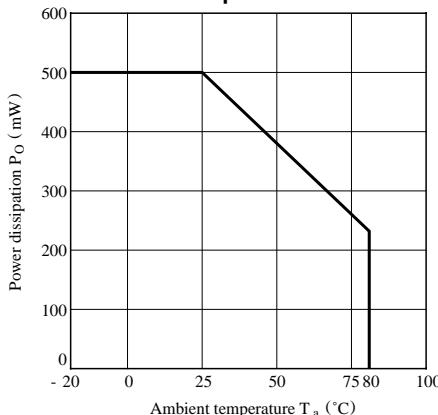


Fig. 8 Forward Current vs. Ambient Temperature



**Fig. 9-a Power Dissipation vs.
Ambient Temperature**



**Fig. 9-b Power Dissipation vs.
Ambient Temperature**

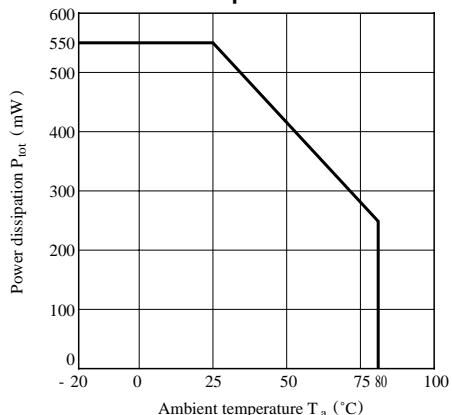
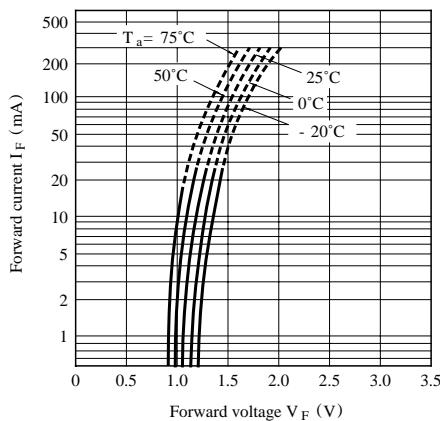
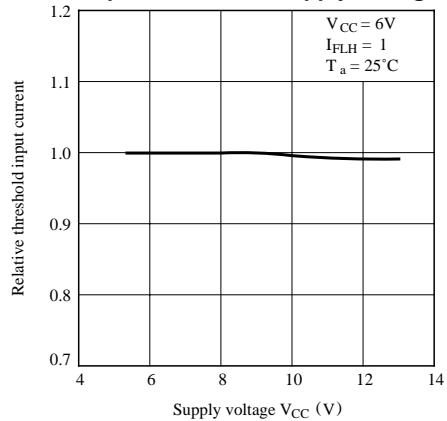


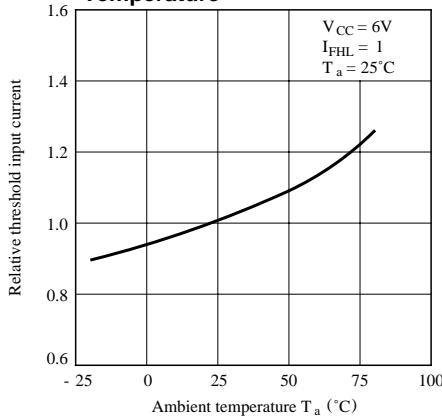
Fig. 10 Forward Current vs. Forward Voltage



**Fig.11 “ Low → High ” Relative Threshold
Input Current vs. Supply Voltage**



**Fig.12 “ Low → High ” Relative Threshold
Input Current vs. Ambient
Temperature**



**Fig.13 O₁ Low Level Output Voltage vs.
O₁ Output Current**

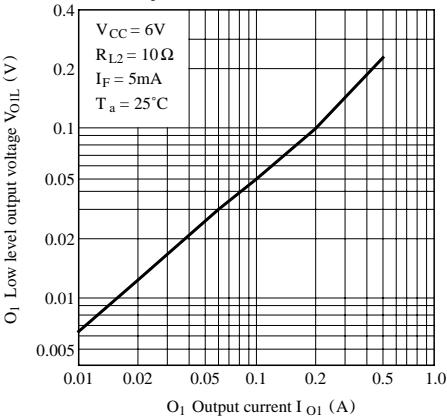


Fig.14 O₁ Low Level Output Voltage vs. Ambient Temperature

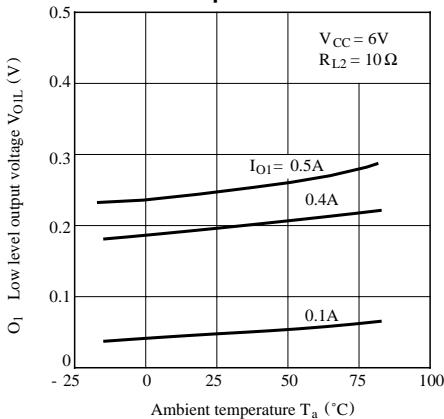


Fig.16 O₂ High Level Output Voltage vs. Ambient Temperature

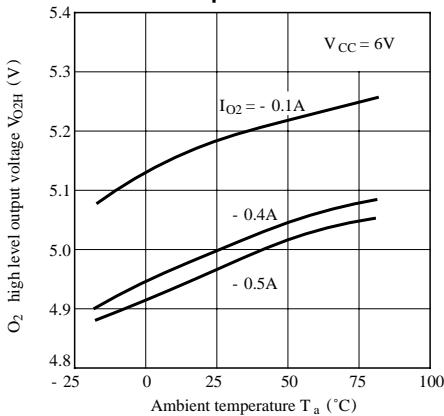


Fig.18 O₂ Low Level Output Voltage vs. Ambient Temperature

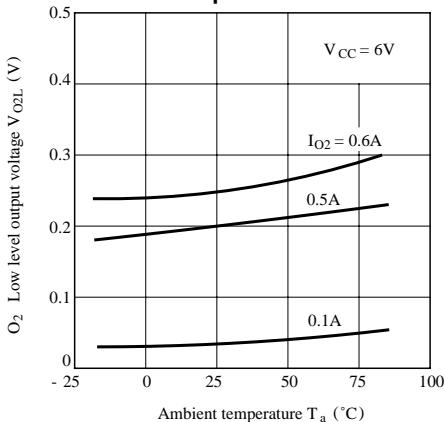


Fig.15 O₂ High Level Output Voltage vs. O₂ Output Current

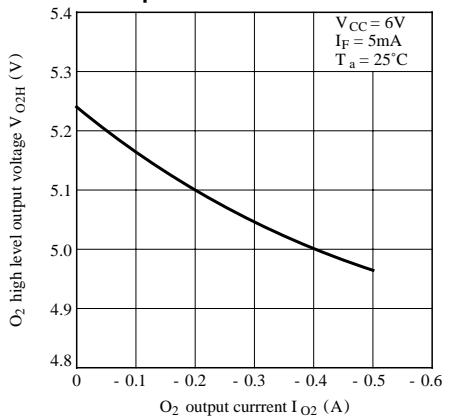


Fig.17 O₂ Low Level Output Voltage vs. O₂ Output Current

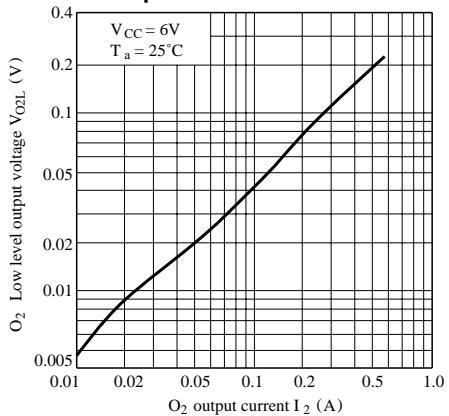


Fig.19 High Level Supply Current vs. Supply Voltage

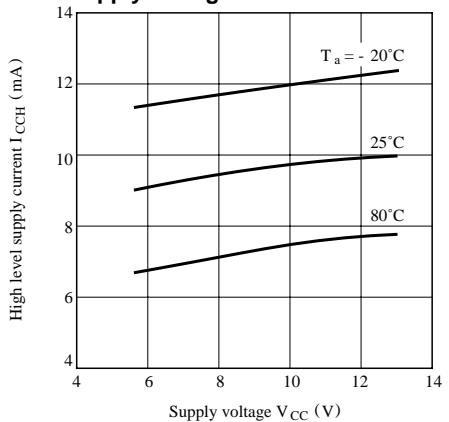


Fig.20 Low Level Supply Current vs. Supply Voltage

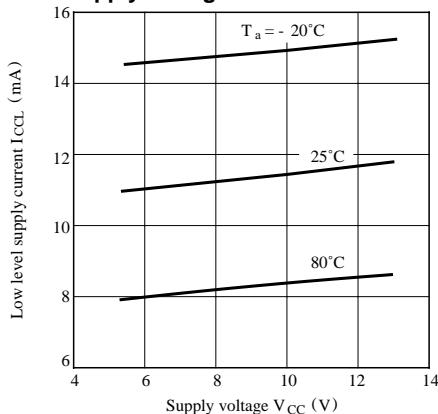


Fig.21 Propagation Delay Time vs. Forward Current

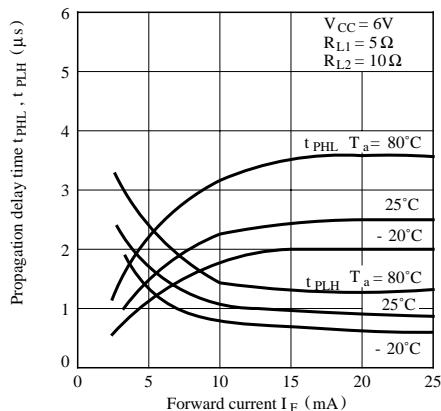


Fig.22 Propagation Delay Time vs. Ambient Temperature

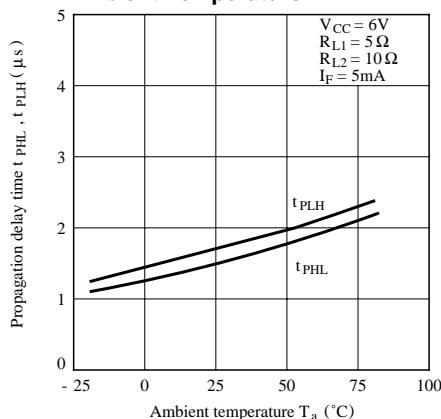
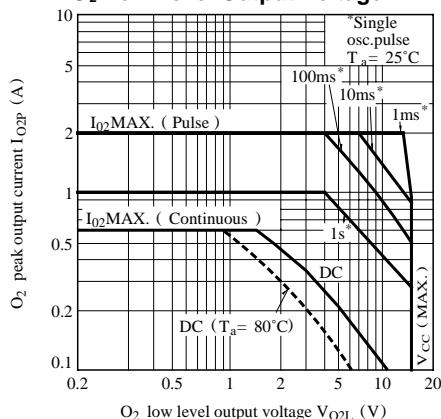
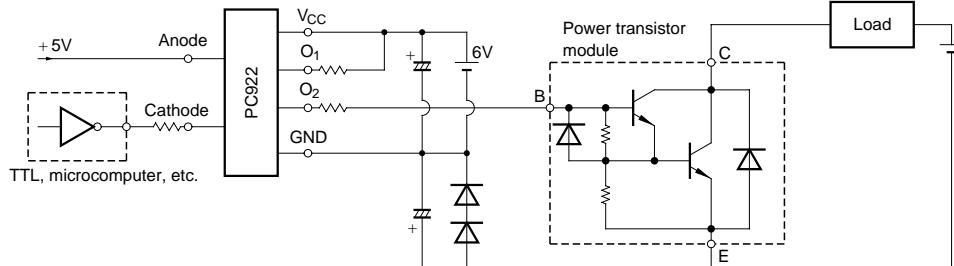


Fig.23 O₂ Peak Output Current vs. O₂ Low Level Output Voltage



■ Application Circuit



■ Precautions for Use

- (1) It is recommended that a by-pass capacitor of more than $0.01 \mu F$ is added between V_{CC} and GND near the device in order to stabilize power supply line.
- (2) Handle this product the same as with other integrated circuits against static electricity.
- (3) As for other general cautions, refer to the chapter "Precautions for Use".